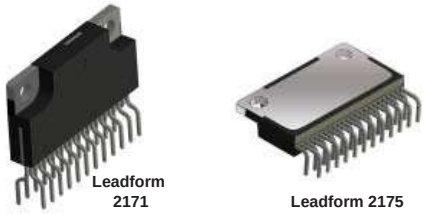
High Voltage 3-Phase Motor Drivers

Features and Benefits

- Built-in pre-drive IC
- MOSFET power element
- CMOS compatible input (3.3 to 5 V)
- High-side gate driver using bootstrap circuit or floating power supply
- Built-in protection circuit for controlling power supply voltage drop
- Built-in overtemperature detection circuit (TD)
- Output of fault signal during operation of protection circuits
- Output current 1.5, 2, or 2.5 A
- Small SIP (SLA 24-pin)

Packages: Power SIP



Leadform 2171 | Leadform 2175

Not to scale

Description

The SLA6820M inverter power module (IPM) series provides a robust, highly-integrated solution for optimally controlling 3-phase motor power inverter systems and variable speed control systems used in energy-conserving designs to drive motors of residential and commercial appliances. These ICs take 230 VAC input voltage, and up to 2.5 A (continuous) output current. They can withstand voltages of up to 500 V (MOSFET breakdown voltage).

The SLA6820M power package includes an IC with all of the necessary power elements (six MOSFETs), pre-driver ICs (two), and flyback diodes (six), needed to configure the main circuit of an inverter. This enables the main circuit of the inverter to be configured with fewer external components than traditional designs.

Applications include residential white goods (home applications) and commercial appliance motor control:

- Air conditioner fan
- Small ventilation fan
- Dishwasher pump

Functional Block Diagram

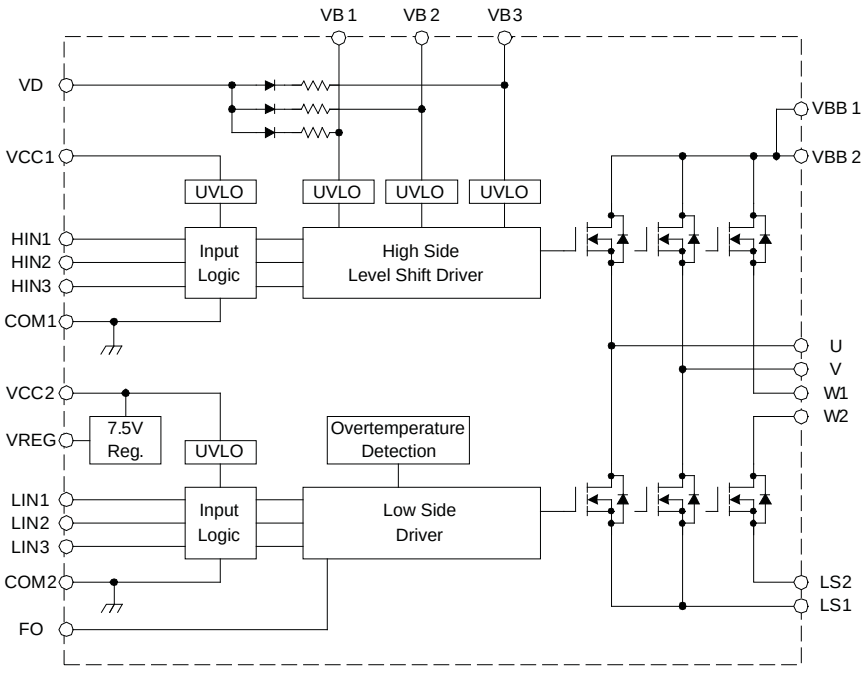


Figure 1. Driver block diagram

Selection Guide

Part Number	Packing	MOSFET Breakdown Voltage, V_{DSS}(min) (V)	Output Current	
			Continuous, I_O(max) (A)	Pulsed, I_{OP} (max) (A)
SLA6826M	18 pieces per tube	250	2	4
SLA6827M	18 pieces per tube	500	1.5	3
SLA6828M	18 pieces per tube	500	2.5	5

Absolute Maximum Ratings, valid at T_A = 25°C

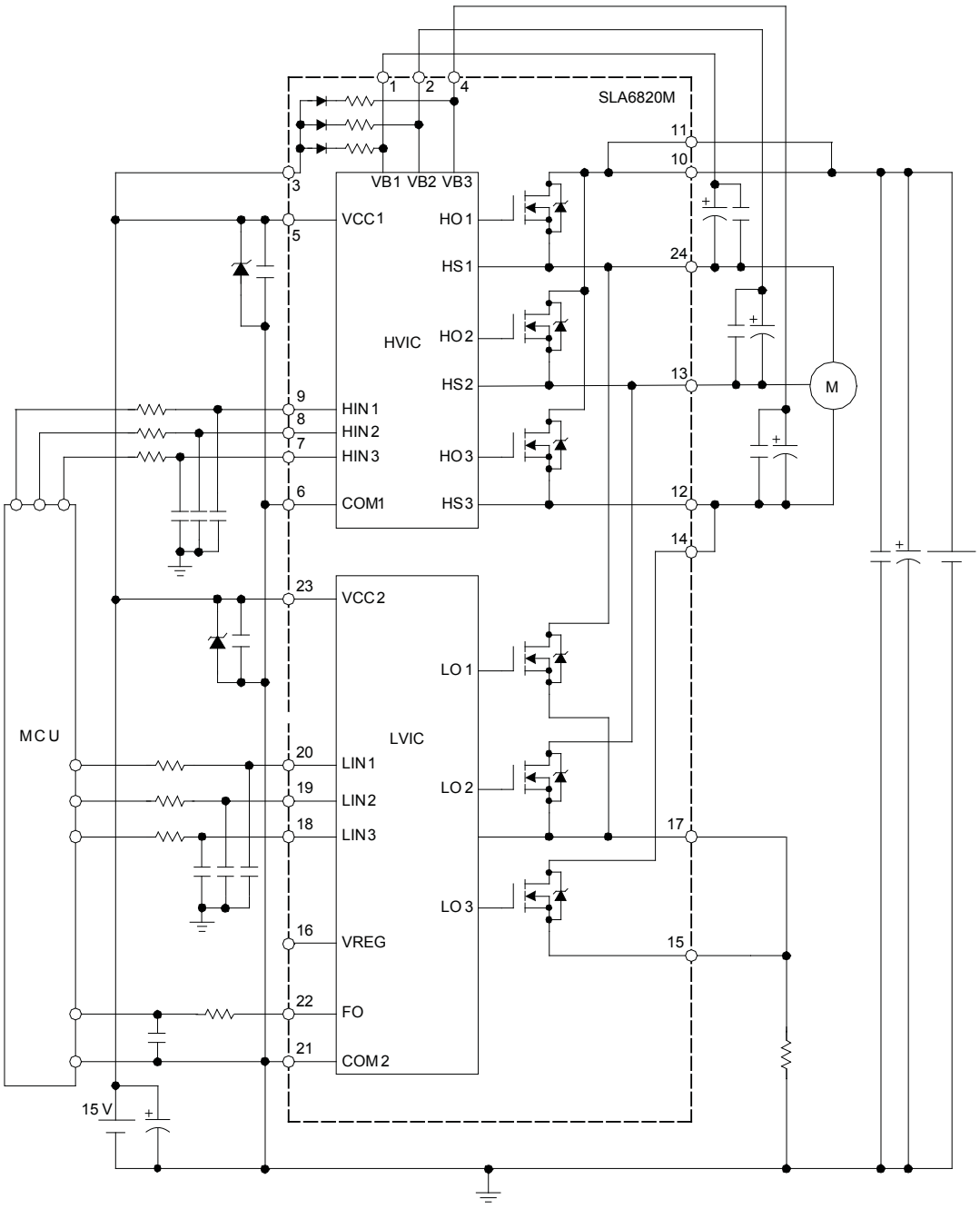
Characteristic	Symbol	Remarks		Rating	Unit
MOSFET Breakdown Voltage	V_{DSS}	SLA6826M	V_{CC} = 15 V, I_D = 100 µA, V_{IN} = 0 V	250	V
		SLA6827M		500	V
		SLA6828M		500	V
Logic Supply Voltage	V_{CC}	Between VCC and COM		20	V
Bootstrap Voltage	V_{BS}	Between VB and HS (U,V, and W phases)		20	V
Output Current, Continuous	I_O	SLA6826M		2	A
		SLA6827M		1.5	A
		SLA6828M		2.5	A
Output Current, Pulsed	I_{OP}	SLA6826M	PW ≤ 100 µs, duty cycle = 1%	4	A
		SLA6827M		3	A
		SLA6828M		5	A
Output Current for Regulator	I_{REG}			35	mA
Input Voltage	V_{IN}	HINx and LINx pins		–0.5 to 7	V
Allowable Power Dissipation	P_D	T_C = 25°C		32.9	W
Thermal Resistance (Junction to Case)	$R_{\theta JC}$	All elements operating		3.8	°C/W
Case Operating Temperature	T_{COP}			–20 to 100	°C
Junction Temperature (MOSFET)	T_J			150	°C
Storage Temperature	T_{stg}			–40 to 150	°C

Recommended Operating Conditions

Characteristic	Symbol	Remarks		Min.	Typ.	Max.	Units
Main Supply Voltage	V_{BB}	SLA6826M	Between VBB and LS	–	140	200	V
		SLA6827M		–	300	400	V
		SLA6828M		–	300	400	V
Logic Supply Voltage	V_{CC}	Between VCC and COM		13.5	–	16.5	V
Dead Time	t_{dead}			1.5	–	–	µs
Junction Temperature	T_J			–	–	125	°C

All performance characteristics given are typical values for circuit or system baseline design only and are at the nominal operating voltage and an ambient temperature, T_A, of 25°C, unless otherwise stated.

Typical Application Diagram



NOTE:

- All of the input pins are connected to GND with internal pull-down resistors rated at 100 kΩ, however, an external pull-down resistor may be required to secure stable condition of the inputs if high impedance conditions are applied to them.
- The external electrolytic capacitors should be placed as close to the IC as possible, in order to avoid malfunctions from external noise interference. Put a ceramic capacitor in parallel with the electrolytic capacitor if further reduction of noise susceptibility is necessary.

ELECTRICAL CHARACTERISTICS, valid at T_A=25°C, unless otherwise noted

Characteristics	Symbol	Conditions		Min	Typ	Max	Units
Logic Supply Voltage	V_{CC}	Between VCC and COM		13.5	15	16.5	V
Logic Supply Current	I_{CC}	V_{CC} = 15 V, I_{REG} = 0 A		–	4	6	mA
Input Voltage	V_{IH}	V_{CC} = 15 V, output on		–	2.0	2.5	V
	V_{IL}	V_{CC} = 15 V, output off		1.0	1.5	–	V
Input Voltage Hysteresis	V_{Ihys}	V_{CC} = 15 V		–	0.5	–	V
Input Current	I_{IH}	High side, V_{CC} = 15 V, V_{IN} = 5 V		–	50	100	µA
	I_{IL}	Low side, V_{CC} = 15 V, V_{IN} = 0 V		–	–	2	µA
Undervoltage Lock Out	V_{UVHL}	High side, between VBx and U, V, or W		9.0	10.0	11.0	V
	V_{UVHH}			9.5	10.5	11.5	V
	V_{UVHhys}	High side, hysteresis		–	0.5	–	V
	V_{UVLL}	Low side, between VCC2 and COM2		10.0	11.0	12.0	V
	V_{UVLH}			10.5	11.5	12.5	V
	V_{UVLhys}	Low side, hysteresis		–	0.5	–	V
FO Terminal Output Voltage	V_{FOL}	V_{CC} = 15 V		0	–	1.0	V
	V_{FOH}			4.0	–	5.5	V
Overtemperature DetectionThreshold Temperature (Activation and Deactivation)	T_{DH}	V_{CC} = 15 V, no heatsink		135	150	165	°C
	T_{DL}			105	120	135	°C
	T_{Dhys}			25	30	35	°C
Output Voltage for Regulator	V_{REG}	I_{REG} = 35 mA, T_C = –20°C to 100°C		6.75	7.5	8.25	V
Bootstrap Diode Leakage Current	I_{LBD}	SLA6826M	V_R = 250 V	–	5	10	µA
		SLA6827M	V_R = 500 V	–	5	10	µA
		SLA6828M	V_R = 500 V	–	–	10	µA
Bootstrap Diode Forward Voltage	V_{FBD}	I_F = 0.15 A		–	1.1	1.3	V
Bootstrap Diode Series Resistor	R_{BD}			–	22	–	Ω
MOSFET Breakdown Voltage	V_{DSS}	SLA6826M	V_{CC} = 15 V, I_D = 100 µA, V_{IN} = 0 V	250	–	–	V
		SLA6827M		500	–	–	V
		SLA6828M		500	–	–	V
MOSFET Leakage Current	I_{DSS}	SLA6826M	V_{CC} = 15 V, V_{DS} = 250 V, V_{IN} = 0 V	–	–	100	µA
		SLA6827M	V_{CC} = 15 V, V_{DS} = 500 V, V_{IN} = 0 V	–	–	100	µA
		SLA6828M	V_{CC} = 15 V, V_{DS} = 500 V, V_{IN} = 0 V	–	–	100	µA
MOSFET On State Resistance	$R_{DS(on)}$	SLA6826M	V_{CC} = 15 V, I_D = 1.5 A, V_{IN} = 5 V	–	1.4	1.8	Ω
		SLA6827M	V_{CC} = 15 V, I_D = 1 A, V_{IN} = 5 V	–	3.6	4	Ω
		SLA6828M	V_{CC} = 15 V, I_D = 1.5 A, V_{IN} = 5 V	–	2.0	2.4	Ω
MOSFET Diode Forward Voltage	V_{SD}	V_{CC} = 15 V, I_{SD} = 1.5 A, V_{IN} = 0 V		–	1.1	1.5	V
MOSFET Diode Recovery Time	t_{rr}	SLA6826M	I_{SD} = 1.5 A, di/dt = 100 A/µs	–	50	–	ns
		SLA6827M	I_{SD} = 1 A, di/dt = 100 A/µs	–	55	–	ns
		SLA6828M	I_{SD} = 1.5 A, di/dt = 100 A/µs	–	75	–	ns

SLA6826M SWITCHING CHARACTERISTICS, valid at T_A=25°C, unless otherwise noted

Characteristics	Symbol	Conditions	Min	Typ	Max	Units
Switching Time, High Side	$t_{dH(on)}$	V_{BB} = 140 V, V_{CC} = 15 V, I_D = 1 A, 0 V ≤ V_{IN} ≤ 5 V	–	650	–	ns
	t_{rH}		–	100	–	ns
	$t_{dH(off)}$		–	370	–	ns
	t_{fH}		–	10	–	ns
Switching Time, Low Side	$t_{dL(on)}$	V_{BB} = 140 V, V_{CC} = 15 V, I_D = 1 A, 0 V ≤ V_{IN} ≤ 5 V	–	600	–	ns
	t_{rL}		–	100	–	ns
	$t_{dL(off)}$		–	300	–	ns
	t_{fL}		–	10	–	ns

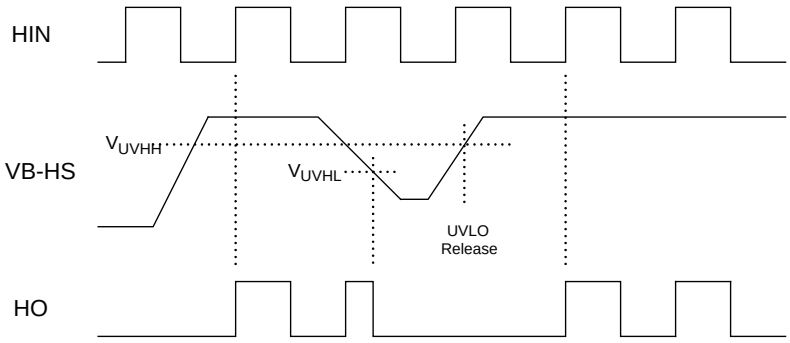
SLA6827M SWITCHING CHARACTERISTICS, valid at T_A=25°C, unless otherwise noted

Characteristics	Symbol	Conditions	Min	Typ	Max	Units
Switching Time, High Side	$t_{dH(on)}$	V_{BB} = 300 V, V_{CC} = 15 V, I_D = 1.5 A, 0 V ≤ V_{IN} ≤ 5 V	–	550	–	ns
	t_{rH}		–	100	–	ns
	$t_{dH(off)}$		–	420	–	ns
	t_{fH}		–	30	–	ns
Switching Time, Low Side	$t_{dL(on)}$	V_{BB} = 300 V, V_{CC} = 15 V, I_D = 1.5 A, 0 V ≤ V_{IN} ≤ 5 V	–	570	–	ns
	t_{rL}		–	100	–	ns
	$t_{dL(off)}$		–	450	–	ns
	t_{fL}		–	30	–	ns

SLA6828M SWITCHING CHARACTERISTICS, valid at T_A=25°C, unless otherwise noted

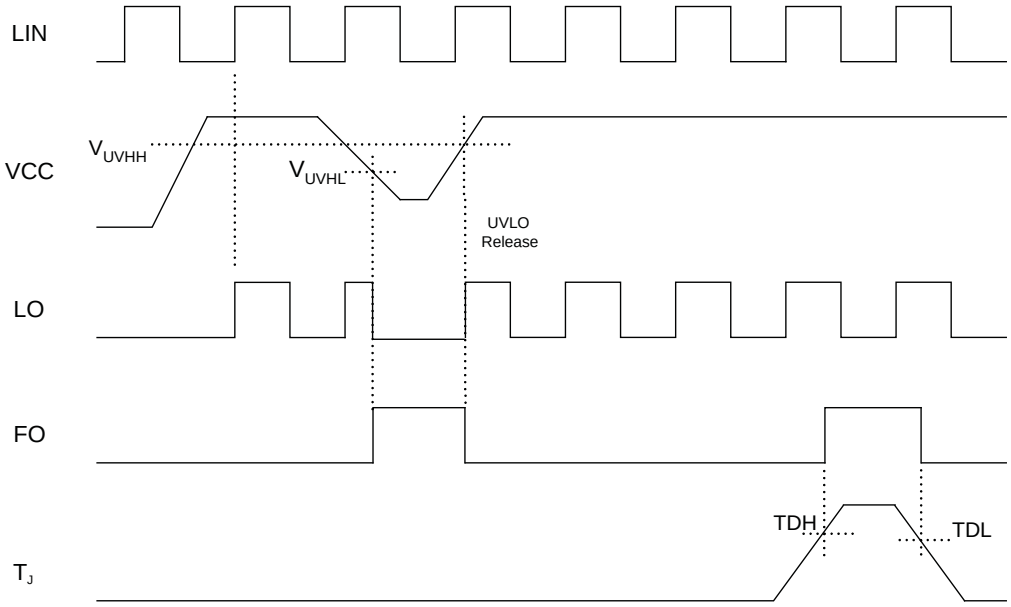
Characteristics	Symbol	Conditions	Min	Typ	Max	Units
Switching Time, High Side	$t_{dH(on)}$	V_{BB} = 300 V, V_{CC} = 15 V, I_D = 2.5 A, 0 V ≤ V_{IN} ≤ 5 V	–	650	–	ns
	t_{rH}		–	130	–	ns
	$t_{dH(off)}$		–	540	–	ns
	t_{fH}		–	50	–	ns
Switching Time, Low Side	$t_{dL(on)}$	V_{BB} = 300 V, V_{CC} = 15 V, I_D = 2.5 A, 0 V ≤ V_{IN} ≤ 5 V	–	690	–	ns
	t_{rL}		–	150	–	ns
	$t_{dL(off)}$		–	590	–	ns
	t_{fL}		–	50	–	ns

High Side Driver Input/Output Timing Diagrams



After UVLO is released, IC operation is started by the first rising edge of input

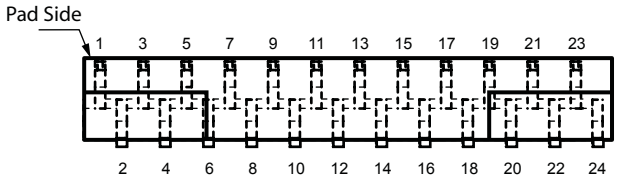
Low Side Driver Input/Output Timing Diagrams



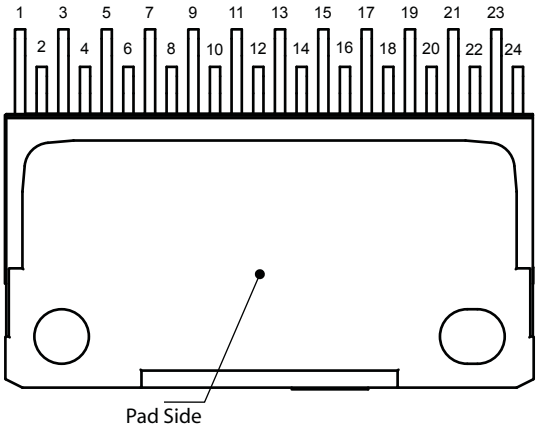
After UVLO is released, IC operation is started by the first rising edge of input

Pin-out Diagrams

Leadform 2171



Leadform 2175



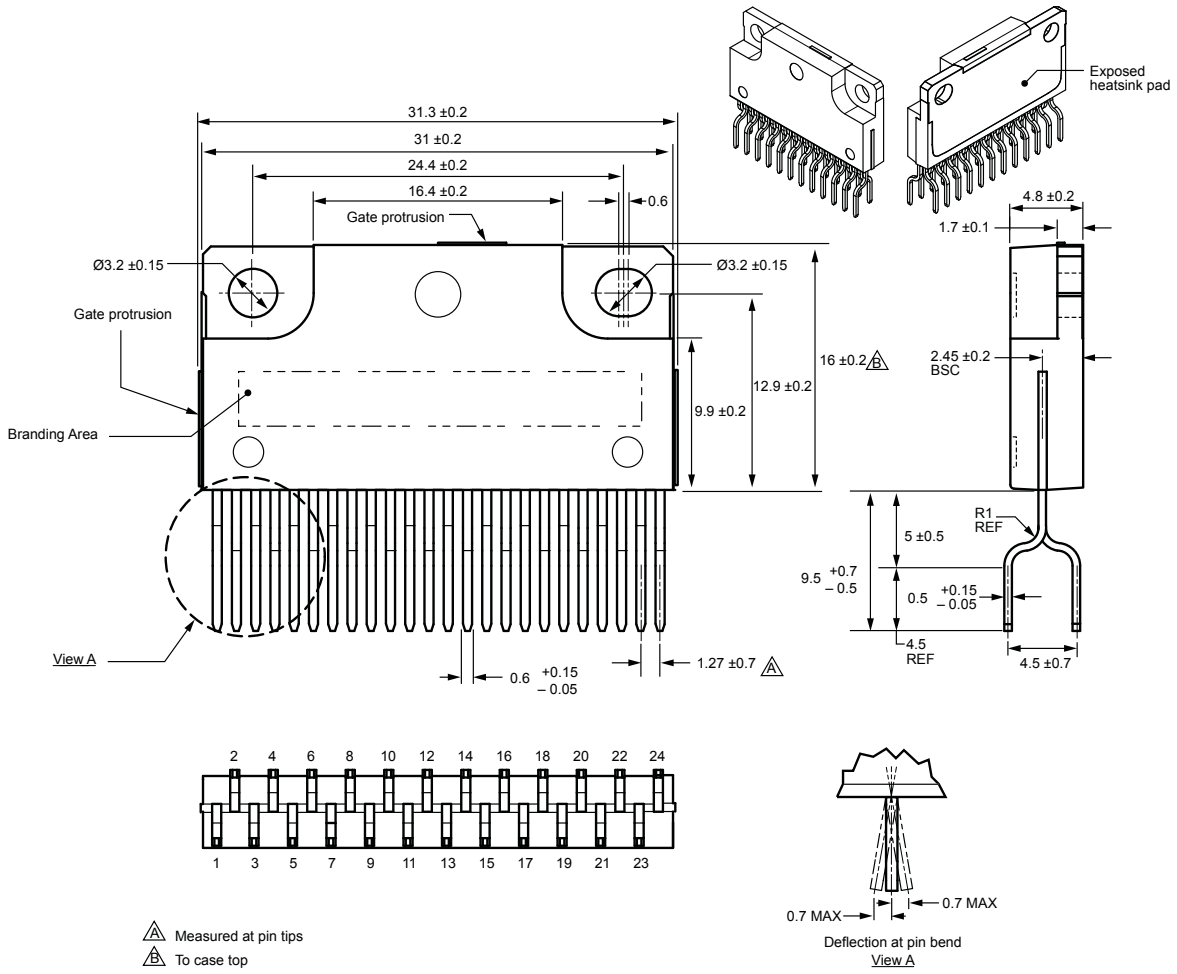
Terminal List Table

Number	Name	Function
1	VB1	High side bootstrap terminal (U phase)
2	VB2	High side bootstrap terminal (V phase)
3	VD	Bootstrap diode anode terminal
4	VB3	High side bootstrap terminal (W phase)
5	VCC1	High side logic supply voltage
6	COM1	High side logic GND terminal
7	HIN3	High side input terminal (W phase)
8	HIN2	High side input terminal (V phase)
9	HIN1	High side input terminal (U phase)
10	VBB1	Main supply voltage 1 (connect to VBB2 externally)
11	VBB2	Main supply voltage 2 (connect to VBB1 externally)
12	W1	Output of W phase (connect to W2 externally)
13	V	Output of V phase
14	W2	Output of W phase (connect to W1 externally)
15	LS2	Low side emitter terminal (connect to LS1 externally)
16	VREG	Internal regulator output terminal
17	LS1	Low side emitter terminal (connect to LS1 externally)
18	LIN3	Low side input terminal (W phase)
19	LIN2	Low side input terminal (V phase)
20	LIN1	Low side input terminal (U phase)
21	COM2	Low side GND terminal
22	FO	Overtemperature detection fault-signal output terminal
23	VCC2	Low side logic supply voltage
24	U	Output of U phase

Package Outline Drawing

Leadform 2171

Dual rows, 24 alternating pins; vertical case mounting; pin #1 on tab side



A Measured at pin tips
B To case top

Leadform: 2171
Terminal core material: Cu
Terminal plating: Ni
Recommended attachment: Solder dip (Sn-Ag-Cu)

Dimensions in millimeters

Branding codes (exact appearance at manufacturer discretion):
1st line, type: SLA682xM

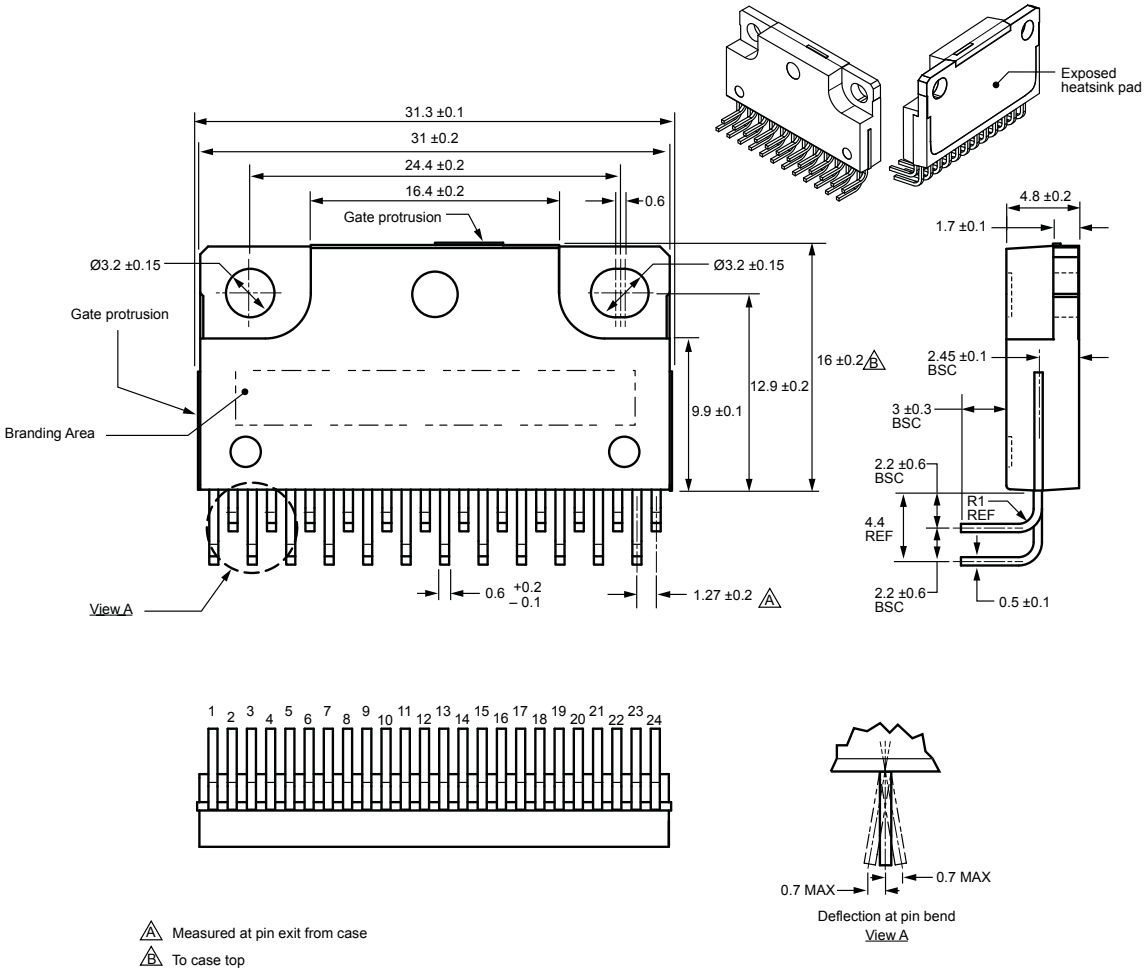
2nd line, lot: *YMDD#*
Where: Y is the last digit of the year of manufacture
M is the month (*1* to *9*, *O*, *N*, *D*)
DD is the date
is the tracking letter

Leadframe plating Pb-free. Device composition complies with the RoHS directive.

Package Outline Drawing

Leadform 2175

Dual rows, 24 alternating pins; pins bent 90° for horizontal case mounting; pin #1 in outer row



A Measured at pin exit from case

B To case top

Leadform: 2175
Terminal core material: Cu
Terminal plating: Ni
Recommended attachment: Solder dip (Sn-Ag-Cu)

Dimensions in millimeters

Branding codes (exact appearance at manufacturer discretion):
1st line, type: SLA682xM

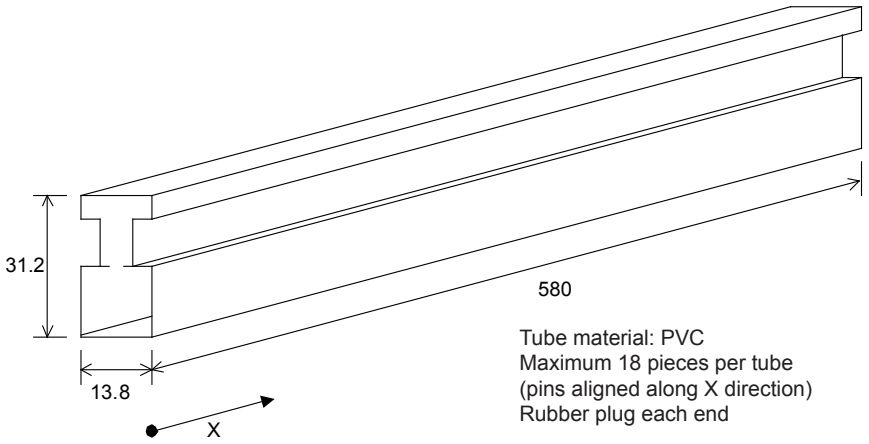
2nd line, lot: *YMDD#*
Where: Y is the last digit of the year of manufacture
M is the month (*1* to *9*, *O*, *N*, *D*)
DD is the date
is the tracking letter

Leadframe plating Pb-free. Device composition complies with the RoHS directive.

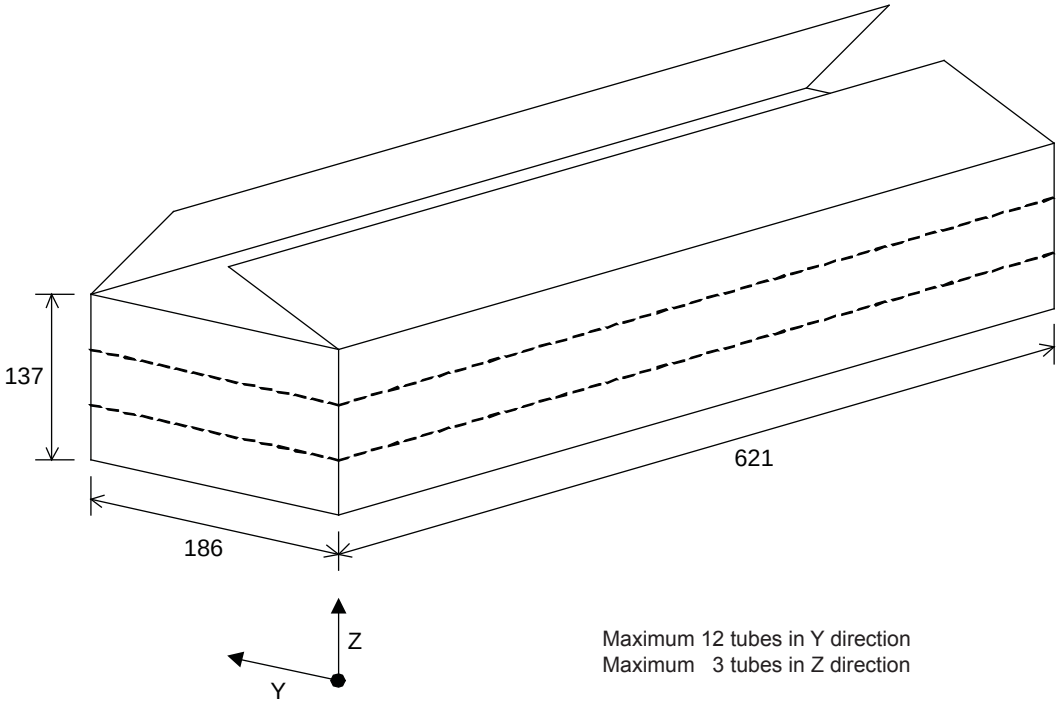
Packing Specification

Leadform 2171

Dimensions in millimeters



Tube material: PVC
Maximum 18 pieces per tube
(pins aligned along X direction)
Rubber plug each end



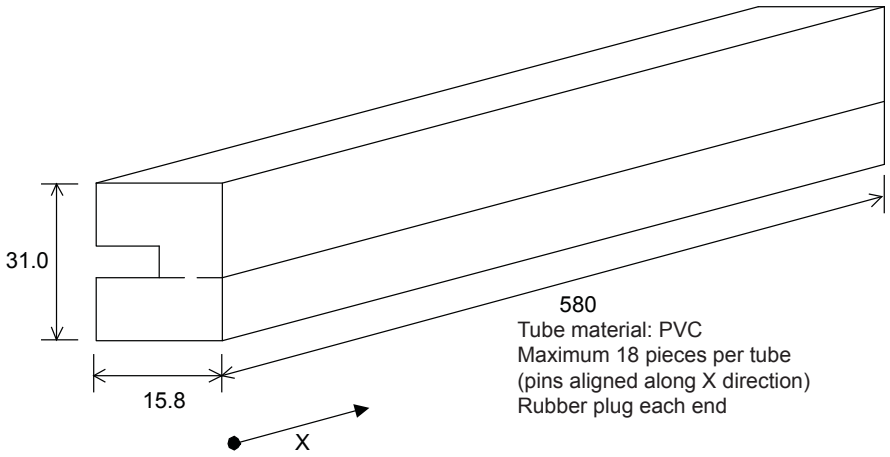
Maximum 12 tubes in Y direction
Maximum 3 tubes in Z direction

Maximum pieces per carton:
18 pieces per tube
12 tubes per layer
x 3 layers of tubes
648 pieces per carton

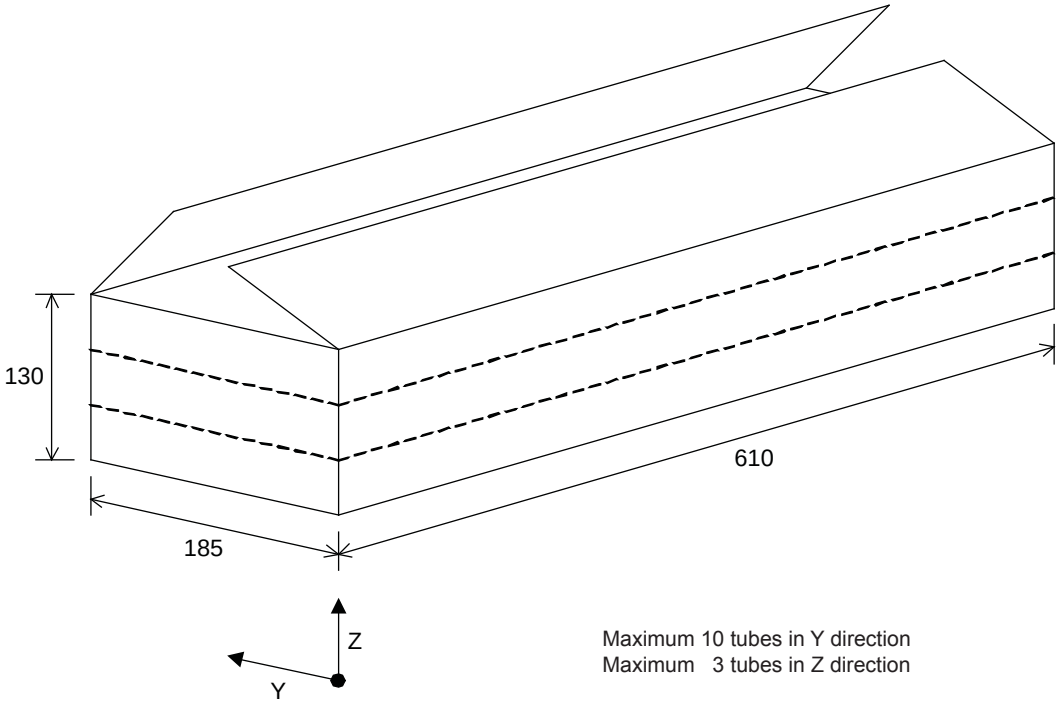
Packing Specification

Leadform 2175

Dimensions in millimeters

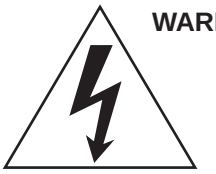


Tube material: PVC
Maximum 18 pieces per tube
(pins aligned along X direction)
Rubber plug each end



Maximum 10 tubes in Y direction
Maximum 3 tubes in Z direction

Maximum pieces per carton:
18 pieces per tube
10 tubes per layer
x 3 layers of tubes
540 pieces per carton



WARNING — These devices are designed to be operated at lethal voltages and energy levels. Circuit designs that embody these components must conform with applicable safety requirements. Precautions must be taken to prevent accidental contact with power-line potentials. Do not connect grounded test equipment.

The use of an isolation transformer is recommended during circuit development and breadboarding.

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5°C to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

Cautions for Testing and Handling

When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing device, shorts between adjacent products, and shorts to the heatsink.

Remarks About Using Silicone Grease with a Heatsink

- When silicone grease is used in mounting this product to a heatsink, it shall be applied evenly and thinly. If more silicone grease than required is applied, it may produce stress.
- Volatile-type silicone greases may permeate the product and produce cracks after long periods of time, resulting in reduced heat radiation effect, and possibly shortening the lifetime of the product.
- Our recommended silicone greases for heat radiation purposes, which will not cause any adverse effect on the product life, are indicated below:

Type	Suppliers
G746	Shin-Etsu Chemical Co., Ltd.
YG6260	Momentive Performance Materials, Inc.
SC102	Dow Corning Toray Silicone Co., Ltd.

Heatsink Mounting Method

Torque When Tightening Mounting Screws. The recommended tightening torque for this product package type is: 58.8 to 78.4 N•cm (6.0 to 8.0 kgf•cm).

Soldering

- When soldering the products, please be sure to minimize the working time, within the following limits:

  260±5°C 10 s

  380±5°C 5 s

- Soldering iron should be at a distance of at least 1.5 mm from the body of the products

Electrostatic Discharge

- When handling the products, operator must be grounded. Grounded wrist straps worn should have at least 1 MΩ of resistance to ground to prevent shock hazard.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of soldering irons or the solder bath must be grounded in other to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in our shipping containers or conductive containers, or be wrapped in aluminum foil.

The products described herein are manufactured in Japan by Sanken Electric Co., Ltd. for sale by Allegro MicroSystems, Inc.

Sanken and Allegro reserve the right to make, from time to time, such departures from the detail specifications as may be required to permit improvements in the performance, reliability, or manufacturability of its products. Therefore, the user is cautioned to verify that the information in this publication is current before placing any order.

When using the products described herein, the applicability and suitability of such products for the intended purpose shall be reviewed at the users responsibility.

Although Sanken undertakes to enhance the quality and reliability of its products, the occurrence of failure and defect of semiconductor products at a certain rate is inevitable.

Users of Sanken products are requested to take, at their own risk, preventative measures including safety design of the equipment or systems against any possible injury, death, fires or damages to society due to device failure or malfunction.

Sanken products listed in this publication are designed and intended for use as components in general-purpose electronic equipment or apparatus (home appliances, office equipment, telecommunication equipment, measuring equipment, etc.). Their use in any application requiring radiation hardness assurance (e.g., aerospace equipment) is not supported.

When considering the use of Sanken products in applications where higher reliability is required (transportation equipment and its control systems or equipment, fire- or burglar-alarm systems, various safety devices, etc.), contact a company sales representative to discuss and obtain written confirmation of your specifications.

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